## **IN THE CLAIMS**

1 (Previously Presented). A method comprising:

temporarily flattening a sheet by applying a flattening force to the center of said sheet;

applying row and column electrodes to said sheet while said sheet is held in a flattened configuration; and

securing said sheet to a second sheet while continuing to hold the center of said sheet in a flattened configuration.

2 (Original). The method of claim 1 wherein temporarily flattening the sheet includes placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.

Claim 3 (Canceled).

- 4 (Previously Presented). The method of claim 1 wherein processing said sheet includes applying a light emitting material to said sheet.
- 5 (Original). The method of claim 4 wherein applying a light emitting material to said sheet includes applying an organic light emitting material between said row and column electrodes.
- 6 (Original). The method of claim 1 further including processing said second sheet in a flattened configuration.
  - 7 (Original). The method of claim 6 including processing said second sheet in a chuck.
- 8 (Original). The method of claim 7 including processing both said first and second sheets in chucks and combining said sheets using said chucks.

- 9 (Original). The method of claim 1 including securing said first and second sheets to an integrator plate.
- 10 (Original). The method of claim 9 including surface mounting said first and second sheets.
- 11 (Original). The method of claim 8 including surface mounting said first and second sheets in said chucks.
  - 12 (Previously Presented). A method comprising:

receiving a warped sheet;

temporarily flattening said sheet for processing by applying a force to the center of said sheet;

processing said center flattened, warped sheet by applying electrodes to said sheet;

securing said center flattened, warped sheet to a planar surface.

- 13 (Original). The method of claim 12 including securing said flattened sheet to a second sheet while continuing to hold said flattened sheet in a flattened configuration.
- 14 (Original). The method of claim 12 wherein temporarily flattening the sheet includes placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.
- 15 (Original). The method of claim 12 including securing said flattened sheet to a rigid, planar integrating plate.
  - 16 (Previously Presented). A method comprising:
    temporarily flattening a ceramic sheet by applying a force to the center of said

sheet;

and

processing a glass panel to define row and column electrodes thereon while continuing to hold the center of said sheet in a flattened configuration; and

securing said sheet to said glass panel while continuing to hold the center of said sheet in a flattened configuration.

- 17 (Original). The method of claim 16 including securing said sheet and said panel to an integrating plate.
- 18 (Original). The method of claim 16 wherein temporarily flattening the ceramic sheet by placing the sheet in a vacuum chuck and applying a vacuum to flatten the sheet.
- 19 (Original). The method of claim 16 wherein processing said panel further includes applying an organic light emitting material between said row and column electrodes.
- 20 (Original). The method of claim 16 further including processing both said sheet and said panel in chucks and combining said sheet and said panel using said chucks.